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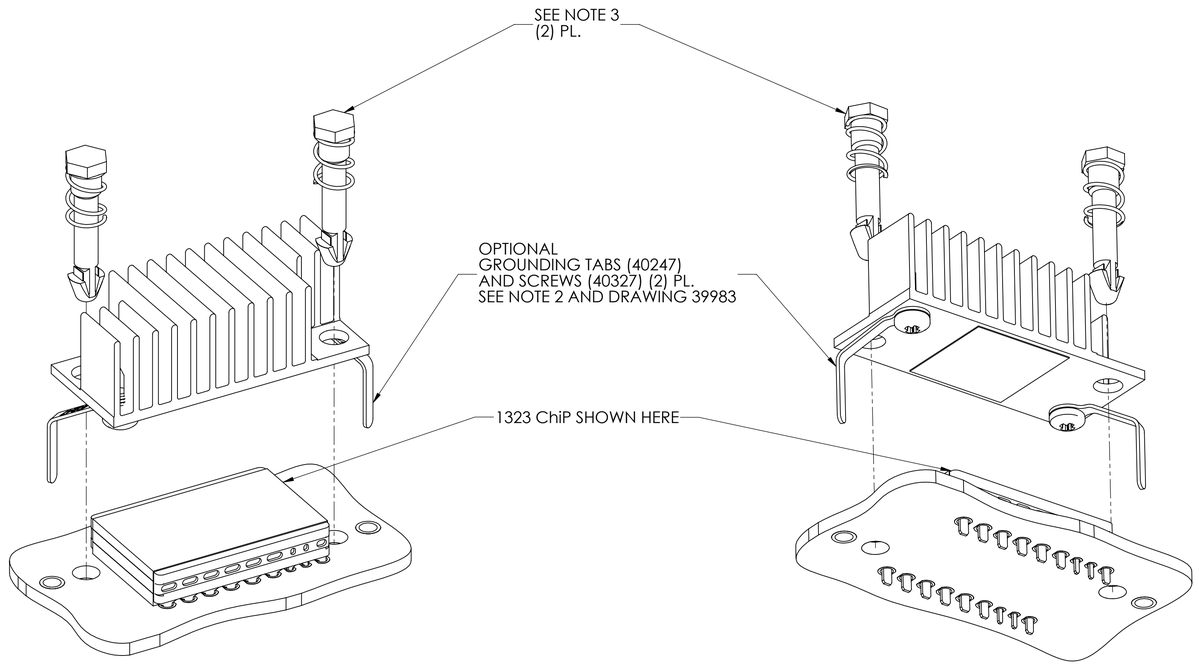
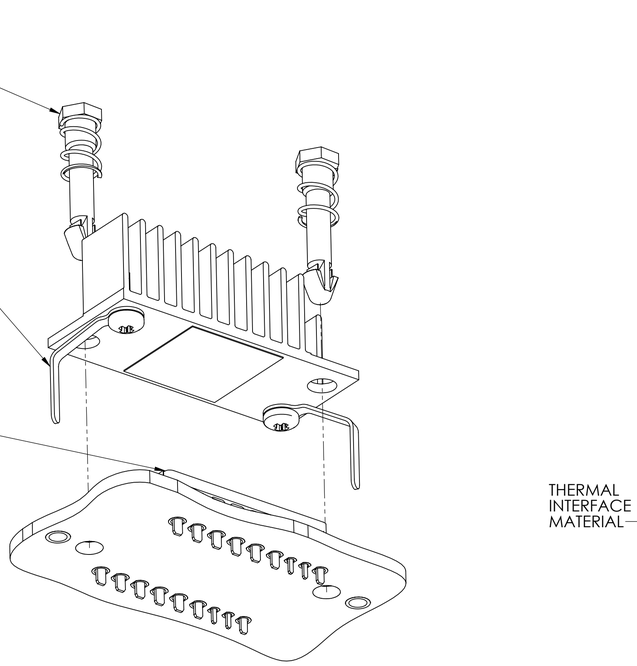
REV.	DESCRIPTION	INTL	DATE	APVD
1	RELEASED PER E140498a	SKR	04/18/14	GCK
2	REVISED PER E200529	DKT	10/19/20	RLT



ISO ASSY REF ONLY



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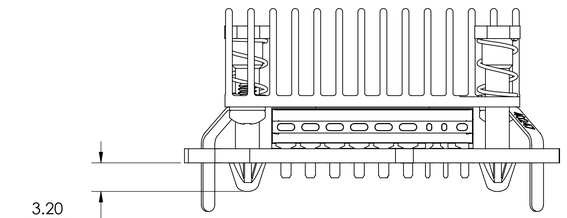
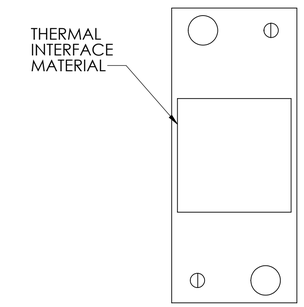
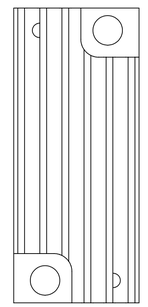
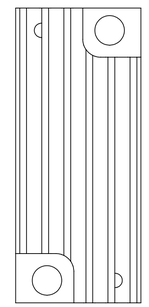




BOTTOM VIEW
(HEATSINK AND THERMAL
INTERFACE MATERIAL ONLY)



LONGITUDINAL FLOW (LF)
(HEAT SINK ONLY SHOWN)



X-FLOW (LF)
(HEAT SINK ONLY SHOWN)

NOTES:

1. FOR PCB LAYOUT SEE VICOR APPLICATION DRAWING 39983.
2. THE SOLDERING METHOD USED FOR CHIPS (AND OPTIONAL HEATSINK GROUNDING) IS IMPORTANT WHEN SELECTING A THERMAL INTERFACE MATERIAL (TIM). THE PHASE-CHANGE TIM SHOWN IN THESE ILLUSTRATIONS MAY BE DAMAGED BY TEMPERATURES OVER 125C, SO TWO ASSEMBLY PROCEDURES ARE DESCRIBED BELOW:
   (A) FOR HAND-SOLDERING ONLY,
   (B) FOR WAVE-SOLDERING AND/OR HAND-SOLDERING.

   (A) PLACE CHIP AND TOP-SIDE HEATSINK (WITH PRE-ATTACHED TIM AND GROUNDING TABS) ON PCB. WHILE SUPPORTING PCB, INSERT PLASTIC PUSH-PINS THROUGH HEATSINK AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.) HAND-SOLDER CHIP AND GROUNDING PINS.

   (B) WAVE SOLDERING TEMPERATURES ARE UNSUITABLE FOR PLASTIC PUSH-PINS AND PHASE-CHANGE TIM, SO PARKER CHOMERICS GEL8010 IS RECOMMENDED AS A TIM. APPLY A UNIFORM .003" (.076MM) LAYER OF TIM TO THE TOP SURFACE OF THE CHIP, OR TO THE BOTTOM SURFACE OF THE HEATSINK. PLACE CHIP ON PCB AND TOP-SIDE HEATSINK ON CHIP. WITH A CUSTOM FIXTURE APPLY APPROX. 3 LBS LOAD TO THE TOP-SIDE HEATSINK AND THEN WAVE-SOLDER ALL PINS. REMOVE FIXTURE AND, WHILE SUPPORTING PCB, INSERT PLASTIC PUSH-PINS THROUGH HEATSINK AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.)
3. CARE SHOULD BE TAKEN TO AVOID FULLY COMPRESSING THE PUSH-PIN SPRING DURING INSTALLATION AS THIS WOULD EXPOSE THE CHIP TO FORCES GREATER THAN THE RECOMMENDED LIMIT OF 1.5 LBF (6.7 N) PER PUSH-PIN.
4. RoHS COMPLIANT PER CST-0001 LATEST REVISION.

PUSH-PIN SELECTION

PUSH-PINS W/ SPRINGS (100/BAG)	COLOR	PCB THK NOMINAL RANGE	PCB THK MINIMUM	PCB THK MAXIMUM
40548	WHITE	1.143 MM TO 1.626 MM [.045"] TO [.064"]	1.016 MM [.040"]	1.803 MM [.071"]
40549	BLACK	1.651 MM TO 2.464 MM [.065"] TO [.097"]	1.499 MM [.059"]	2.743 MM [.108"]
40550	BLUE	2.489 MM TO 3.150 MM [.098"] TO [.124"]	2.235 MM [.088"]	3.505 MM [.138"]
40551	GRAY	3.175 MM TO 3.708 MM [.125"] TO [.146"]	2.870 MM [.113"]	4.115 MM [.162"]

HEATSINK SELECTION

CHIP SIZE	HEAT SINK TYPE	P/N HEATSINK ONLY	P/N HEATSINK W/ TIM ONLY	P/N HEATSINK, TIM, AND GROUND TAB	P/N HEATSINK W/ GROUND TAB ONLY
SOLDERING METHOD (SEE NOTE 2)	-	2(B) WITH VICOR 40325 THERMAL GEL	2(A) HAND SOLDER ONLY	2(A) HAND SOLDER ONLY	2(B) WITH VICOR 40325 THERMAL GEL
1323	LF 11MM	39963	40758	40756	40757
	XF 11MM	39964	40761	40759	40760

DRAWN BY	DATE
Robert Wasik	09/11/2013

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE : INCH / [MM]
TOLERANCES ARE:
DECIMALS X.XX [X.X] ± 0.01 [0.25] ANGLES ±1°
X.XXX [X.XX] ± 0.005 [0.127]
THIRD ANGLE PROJECTION
DO NOT SCALE DRAWING

VICOR SWD

APP DWG, CHIP PUSHPIN TOPSIDE HEATSINK, 1323

SIZE	CAGE CODE	DWG NO	REV
D	67131	40415	2

SCALE 3:1 SHEET 1 OF 1